



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED_SIZE	ROTATION	PLATED	QTY
+	12.0	-	PLATED	272
+	25.591	-	PLATED	3
+	35.433	-	PLATED	2
+	40.0	-	PLATED	12
+	43.307	-	PLATED	6
+	43.701	-	PLATED	6
+	46.063	-	PLATED	8
+	72.835	-	PLATED	5
+	86.614	-	PLATED	2
+	125.984	-	PLATED	4
+	25.591	-	NON-PLATED	4
8	55.118x23.622	90.000	PLATED	4
8	66.929x23.622	90.000	PLATED	4

- NOTES:
- 1.BOARD DIMENSIONS ARE IN MM
  - 2.FOUR LAYER, 1.6MM PCB THICKNESS, NO IMPEDANCE CONTROL

- NOTES:
- 1.Specifications:
    - 1.0 Producibility study- it is the responsibility of the supplier to conduct thorough review of the artwork and media for manufacturablity in the supplier's process compliance to all applicable specifications. The customer must be advised in writing (inadvance of manufacturing) of any changes, revisions, or corrections made or recommendations to ensure conformance to the customers standards, and of any specifications that cannot met.
    - 1.1 This drawing is to be used in conjuction with the provided gerber and drill data when applicable.
  - 2.Material:
    - 2.0 NEMA Grade FR-4/Epoxy class , foil lamination structure for core and copper thickness: type GFN, Grade A, Class 1, Class A.
    - 2.1 Color is vendor's option.
  - 3.Soldermask:
    - 3.0 Soldermask both sides with (green color) liquid photoimageble soldermask .003 max. thickness. Soldermask over bare copper.
  4. Drilling:
    - 4.0 All hole diameters are finished sizes.
    - 4.1 All holes to be +/- .003 from the true postion unless otherwise specified.
    - 4.2 All holes diameters to be +/- .003 unless otherwise specified.
    - 4.3 An CNC drill file has been supplied - see drill table.
  - 5.Finish:
    - 5.0 Plate thru with copper .0010 min to .002 max thickness drill size. dimensions apply after plating.
    - 5.1 Finished boardsshall not have nicks, scratches, voids, exposed copper, poor plating, or misdrilled holes.
    - 5.2 If applicable, Gold plat edge fingers over low stress nickel:

Minimum gold thickness : .00003

Maximum nickel thickness: .0005
  - 6.Silkscreen:
    - 6.0 Silksceen using white non-conductive epoxy or equivalent ( both sides ).
    - 6.1 No Silkscreen allowed on exposed lands or in holes (burnout with soldermask)
    - 6.2 Minimum clearance between silkscreen legend and vias, pads or holes , to be .005.
    - 6.3 Registration to be +/- .005 and must pass peel test.
  - 7.Electrical Test:
    - 7.0 All boards shall be 100% elecrically tested for open/shorts.
    - 7.1 Apply test stamp in non legend area on the solder side of PCB.
  - 8.Cleanlines:
    - 8.0 Boards shall be free of fiber glass dust or any other forgien material.
    - 8.1 Finished boards must conform to 0.01 MG/IN max NaCl ionic contamonation as measured bu omega meter 600SMD.
  - 9.Packaging:
    - 9.0 There shall be max of 25 units per package wrapped in sulpher and silicon free material and contained in heavy cardboard cartons with sufficient surrounding material to prevent shipping damage.
  - 10.Bow and Twist:
    - 10.0 Bow and twist to be .007 IN/IN or .090 max according to IPC-A-600K.
  - 11.Inspection:
    - 11.0 Automatic optical inspection of all layers is required.
  - 12.0 Test coupons need to be provided.
  - 12.1 Add the Auto serial number in the area provided near "SL/NO" in the format of "YYMMXXX"where YY is two numeric year MM is two numeric month and XXX is three numeric running serial number.
  - 13.0 Surface finish ENIG